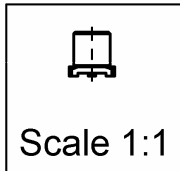
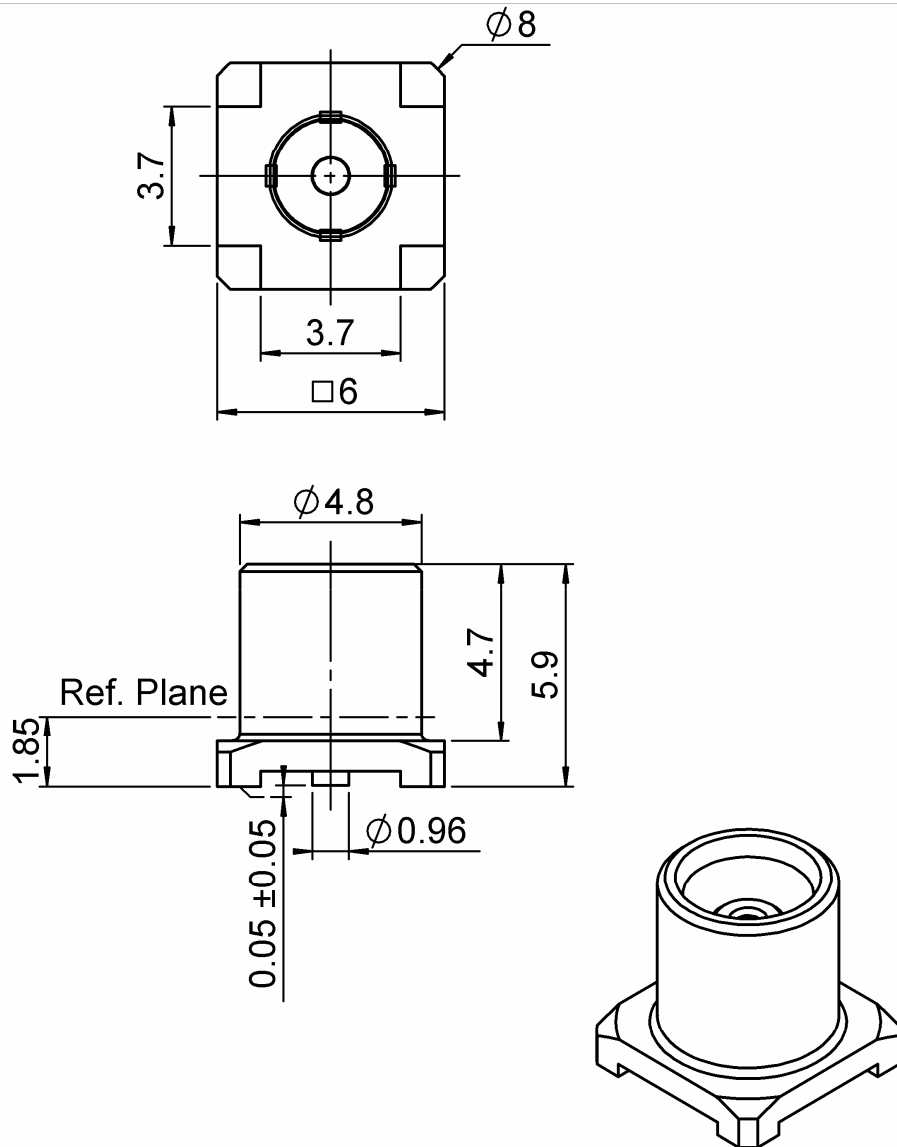


**STRAIGHT JACK RECEPTACLE FOR PCB**

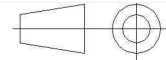
**NON MAGNETIC SMT TYPE**

**R113.424.097**

Series : MCX



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY	NON MAGNETIC BRONZE	GBR
CENTER CONTACT	BERYLLIUM COPPER	GOLD OVER COPPER
OUTER CONTACT		
INSULATOR	PTFE	
GASKET		
OTHERS PARTS		
.	.	.
.	.	.

Issue : 1145 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

**RADIAL**

**STRAIGHT JACK RECEPTACLE FOR PCB****R113.424.097****NON MAGNETIC SMT TYPE**

Series : MCX

**PACKAGING**

Standard	Unit	Other
<b>100</b>	<b>'W' option</b>	<b>Contact us</b>

**SPECIFICATION****ELECTRICAL CHARACTERISTICS**

Impedance	<b>50</b>	$\Omega$
Frequency	<b>0-6</b>	GHz
VSWR	<b>**1.05</b> + <b>0,0300</b>	x F(GHz) Maxi
Insertion loss	<b>*0.05</b>	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- ( <b>NA</b> )	- F(GHz)) dB Maxi
Voltage rating	<b>335</b>	Veff Maxi
Dielectric withstanding voltage	<b>1000</b>	Veff mini
Insulation resistance	<b>1000</b>	M $\Omega$ mini

**ENVIRONMENTAL**

Operating temperature	<b>-55/+125</b>	$^{\circ}\text{C}$
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**OTHER CHARACTERISTICS**Assembly instruction **NA**

Others :

\* Coaxial Transmission Line Only

\*\* Performance strongly

depends on lay out and pcb material

Distortion of the magnetic field :

&lt;= 0.5 ppm@ 10 mm @ Bo = 1.5 Tesla

**MECHANICAL CHARACTERISTICS**

Center contact retention	
Axial force – Mating end	<b>10</b> N mini
Axial force – Opposite end	<b>10</b> N mini
Torque	<b>NA</b> N.cm mini

## Recommended torque

Mating	<b>NA</b> N.cm
Panel nut	<b>NA</b> N.cm

Mating life	<b>500</b> Cycles mini
Weight	<b>0,6140</b> g

Issue : 1145 A

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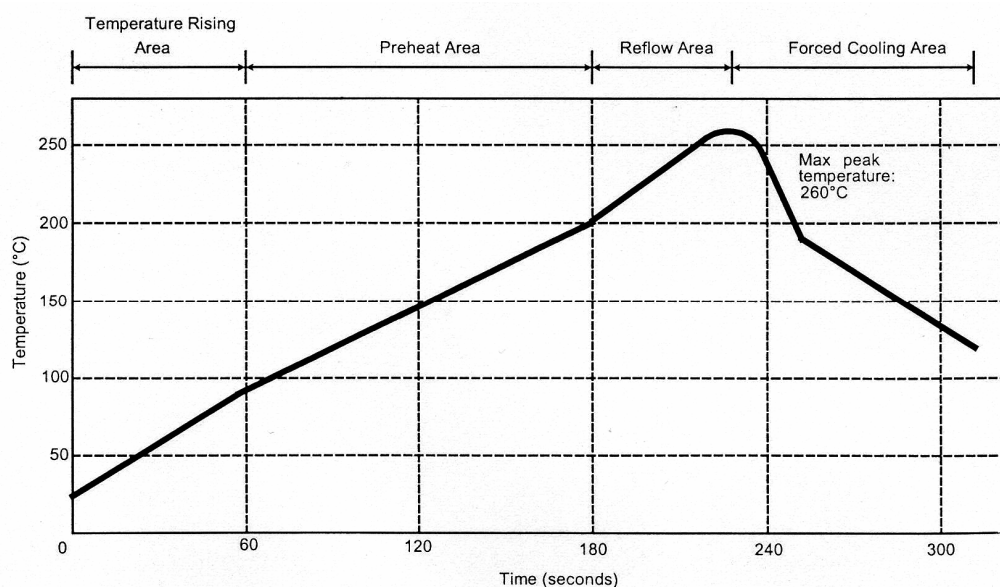
**RADIAL** 

**STRAIGHT JACK RECEPTACLE FOR PCB****NON MAGNETIC SMT TYPE****R113.424.097**

Series : MCX

**SOLDER PROCEDURE**

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.  
We recommend a low residue flux. We advise a thickness of 150 microns mini. ( .006 inch mini ).  
Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.  
Aspiration port (see page 4) centered into body and push against it.  
A video camera is recommended for positioning of the component .  
Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.  
Below please find ,the typical profile to use.
4. Cleaning of printed circuit boards.
5. Verification of solder joints and position of the component by visual inspection.

**TEMPERATURE PROFILE**

Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

**Issue : 1145 A**

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